LM137HVQML 3-Terminal Adjustable Negative Regulators (High Voltage)

Check for Samples: LM137HVQML

FEATURES

- Output Voltage Adjustable from −47V to −1.2V
- 1.5A Output Current Specified, −55°C ≤ T_J ≤ +150°C
- Line Regulation Typically 0.01%/V
- Load Regulation Typically 0.3%
- Excellent Thermal Regulation, 0.002%/W
- 77 dB Ripple Rejection
- Excellent Rejection of Thermal Transients
- 50 ppm/°C Temperature Coefficient
- Temperature-Independent Current Limit
- Internal Thermal Overload Protection
- Standard 3-Lead Transistor Package
- Output Short Circuit Protected

DESCRIPTION

The LM137HV is an adjustable 3-terminal negative voltage regulator capable of supplying in excess of −1.5A over an output voltage range of −47V to −1.2V. This regulators is exceptionally easy to apply, requiring only 2 external resistors to set the output voltage and 1 output capacitor for frequency compensation. The circuit design has been optimized for excellent regulation and low thermal transients. Further, the LM137HV features internal current limiting, thermal shutdown and safe-area compensation, making them virtually blowout-proof against overloads.

The LM137HV serves a wide variety of applications including local on-card regulation, programmable-output voltage regulation or precision current regulation. The LM137HV is an ideal complement to the LM117HV adjustable positive regulator.

Connection Diagrams

See Physical Dimensions section for further information

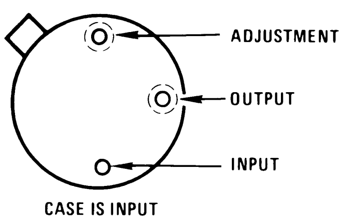


Figure 1. TO Package – Bottom View
See Package Number NDT0003A

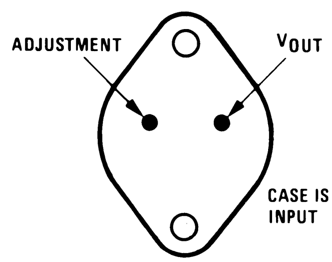
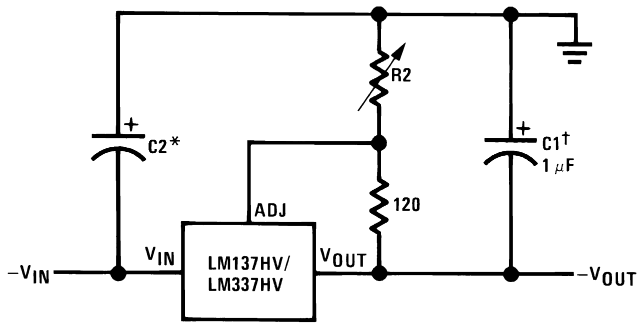


Figure 2. TO-3 Package (Bottom View)
See Package Number K

Typical Applications



$$-V_{OUT} = -1.25V \left(1 + \frac{R2}{120\Omega}\right) + \left[-I_{Adj}\,(R_2)\right]$$

†C1 = 1 μF solid tantalum or 10 μF aluminum electrolytic required for stability. Output capacitors in the range of 1 μF to 1000 μF of aluminum or tantalum electrolytic are commonly used to provide improved output impedance and rejection of transients.

*C2 = 1 μF solid tantalum is required only if regulator is more than 4″ from power-supply filter capacitor.

Figure 3. Adjustable Negative Voltage Regulator

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings(1)

Power Dissipation(2)				Internally limited
Input—Output Voltage Differential				50V
Operating Ambient Temperature Range				$-55°C \le T_A \le +125°C$
Maximum Junction Temperature Range				+150°C
Storage Temperature				$-65°C \le T_A \le +150°C$
Lead Temperature (Soldering, 10 sec.)				300°C
Thermal Resistance	θ_{JA}	NDT0003A pkg. (Still Air @ 0.5W)		174°C/W
		NDT0003A pkg. (500LF / Min Air Flow @ 0.5W)		64°C/W
		K pkg. (Still Air @ 0.5W)		42°C/W
		K pkg. (500LF / Min Air Flow @ 0.5W)		14°C/W
	θ_{JC}	NDT0003A pkg. (@ 1.0W)		15°C/W
		K pkg.		4°C/W
		Package Weight (Typical)	NDT0003A pkg	955mg
			K pkg	12,750mg
ESD Rating(3)				4000V

(1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The ensured specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

(2) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (package junction to ambient thermal resistance, and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $P_{Dmax} = (T_{Jmax} - T_A) / \theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower.

(3) Human body model, 100pF discharged through 1.5KΩ

Table 1. Quality Conformance Inspection

Mil-Std-883, Method 5004 and Method 5005		
Subgroup [(1)]	Description	Temp (°C)
1	Static tests at	+25°C
2	Static tests at	+125°C
3	Static tests at	-55°C
4	Dynamic tests at	+25°C
5	Dynamic tests at	+125°C
6	Dynamic tests at	-55°C
7	Functional tests at	+25°C
8A	Functional tests at	+125°C
8B	Functional tests at	-55°C
9	Switching tests at	+25°C
10	Switching tests at	+125°C
11	Switching tests at	-55°C

(1) Group “A” sample only, test at all temperature.

LM137HVH 883 Electrical Characteristics DC Parameters

The following conditions apply, unless otherwise specified. V_{IN} = −4.0V, I_O = 0.53A, V_O = V_{Ref}

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
V_{Ref}	Reference Voltage	V_{IN} = -4.25V, I_O = 8 mA		-1.272	-1.23	V	1
				-1.28	-1.225	V	2, 3
		V_{IN} = -42V, I_O = 8mA		-1.272	-1.23	V	1
				-1.28	-1.225	V	2, 3
I_Q	Minimum Load Current	V_O = -1.7V, V_{IN} = -4.25V			3.0	mA	1, 2, 3
		V_O = -1.7V, V_{IN} = -11.75V			3.0	mA	1, 2, 3
		V_O = -1.7V, V_{IN} = -42V			5.0	mA	1, 2, 3
R_{Line}	Line Regulation	-42V ≤ V_{IN} ≤ -4.25V, I_O = 8mA			9.4	mV	1, 2, 3
I_{Adj}	Adjustment Pin Current	V_{IN} = -42V, I_O = 8mA			100	µA	1, 2, 3
		V_{IN} = -4.25V, I_O = 8mA			100	µA	1, 2, 3
		V_{IN} = -54V, I_O = 8mA			100	µA	1
ΔI_{Adj}	Adjustment Pin Current Change	-42V ≤ V_{IN} ≤ -4.25V, I_L = 8mA			6.0	µA	1, 2, 3
		V_{IN} = -6.25V, 8mA ≤ I_O ≤ 0.53A			5.0	µA	1, 2, 3
		-54V ≤ V_{IN} ≤ -4.25V, I_O = 8mA			6.0	µA	1
R_{Load}	Load Regulation	V_{IN} = -54V, 10mA ≤ I_O ≤ 60mA			25	mV	1
		V_{IN} = -6.25V, 8mA ≤ I_O ≤ 0.53A			25	mV	1
V_{Rth}	Thermal Regulation	I_O = 0.53A, V_{IN} = -14.5V			5	mV	1
I_{CL}	Current Limit	V_{IN} ≤ -14.25	See [(1)]	0.5	1.6	A	1
		V_{IN} = -51.25V	See [(1)]	0.1	0.5	A	1

(1) Specified parameter not tested.

LM137HVH 883 Electrical Characteristics AC Parameters

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
R_R	Ripple Rejection	V_{IN} = -6.25V, V_O = V_{Ref}, f = 120Hz, e_I = 1V_{RMS}, I_L = 125mA	See (1) (2)		66	dB	4, 5, 6

(1) Tested at +25°C, specified, but not tested at +125°C and −55°C
(2) Bench test per (SG)RPI-3–362 Use TDN 70256657 (NSSG)

LM137HVK 883 Electrical Characteristics DC Parameters

The following conditions apply, unless otherwise specified. V_{IN} = −40V, I_L = 8.0mA, V_O = V_{Ref} = −1.25V (nominal)

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
V_{Ref}	Reference Voltage	V_{IN} = -4.25V		1.272	-1.23	V	1
				-1.28	-1.225	V	2, 3
		V_{IN} = -42V		-1.272	-1.23	V	1
		V_{IN} = -41.3V		-1.28	-1.225	V	2, 3
R_{Line}	Line Regulation	-42V ≤ V_{IN} ≤ -4.25V			9.4	mV	1
		-41.3V ≤ V_{IN} ≤ -4.25V			9.4	mV	2, 3
R_{Load}	Load Regulation	V_{IN} = -54V, 10mA ≤ I_O ≤ 110mA		-25	25	mV	1
		V_{IN} = -6.25V, 8mA ≤ I_O ≤ 1.5A		-25	25	mV	1, 2, 3
V_{Rth}	Thermal Regulation	I_O = 1.5A, V_{IN} = -14.5V, t = 10mS		-5.0	5.0	mV	1
I_{Adj}	Adjustment Pin Current	V_{IN} = -42V			100	µA	1
		V_{IN} = -41.3V			100	µA	2, 3
		V_{IN} = -4.25V			100	µA	1, 2, 3
		V_{IN} = -54V			100	µA	1
ΔI_{Adj}	Adjustment Pin Current Change	-42V ≤ V_{IN} ≤ -4.25V		-5.0	5.0	µA	1
		-41.3V ≤ V_{IN} ≤ -4.25V		-5.0	5.0	µA	2, 3
		-54V ≤ V_{IN} ≤ -4.25V		-6.0	6.0	µA	1
		V_{IN} = -6.25V, 8mA ≤ I_O ≤ 1.5A		-5.0	5.0	µA	1, 2, 3
I_Q	Minimum Load Current	V_O = 1.7V, V_{IN} = -4.25V			3.0	mA	1, 2, 3
		V_O = -1.7V, V_{IN} = -11.75V			3.0	mA	1, 2, 3
		V_O = -1.7V, V_{IN} = -42V			5.0	mA	1
		V_O = -1.7V, V_{IN} = -41.3V			5.0	mA	2, 3
I_{SC}	Short Circuit	V_{IN} = -5V		-2.85	-1.6	A	1
				-3.5	-1.6	A	2, 3
		V_{IN} = -51.25V	See (1)	-0.8	-0.2	A	1

(1) Specified parameter not tested.

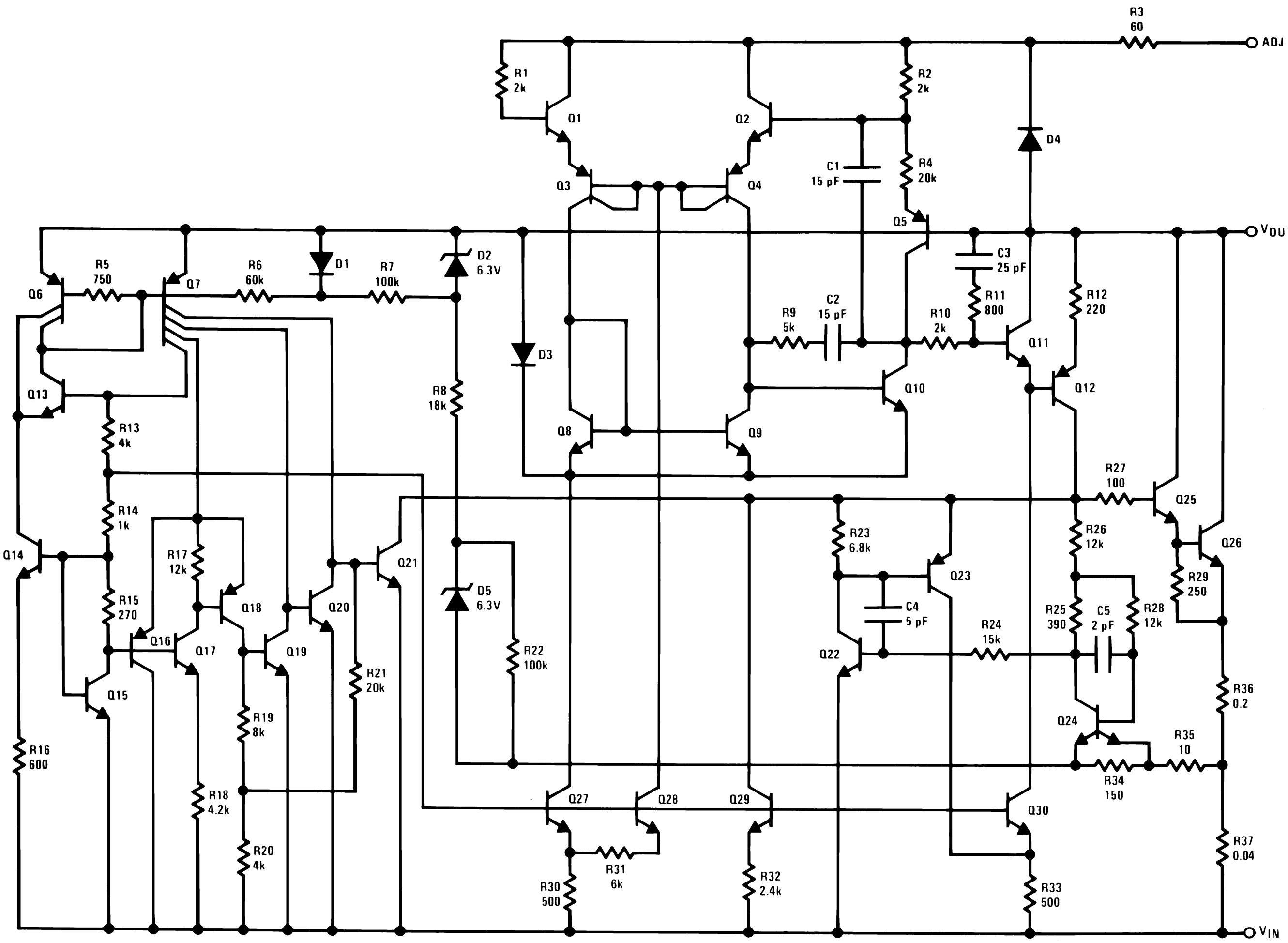
LM137HVK 883 Electrical Characteristics AC Parameters:

The following conditions apply, unless otherwise specified. V_{IN} = −40V, I_L = 8.0mA, V_O = V_{Ref} = −1.25V (nominal)

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
R_R	Ripple Rejection	V_{IN} = -6.25V, V_O = V_{Ref}, f = 120Hz, e_{in} = 1V $_{RMS}$, I_L = 0.5A	See (1) (2)	66		dB	4, 5, 6

(1) Tested at +25°C, specified, but not tested at +125°C and −55°C
(2) Bench test per (SG)RPI-3–362 Use TDN 70256657 (NSSG)

Schematic Diagram



Thermal Regulation

When power is dissipated in an IC, a temperature gradient occurs across the IC chip affecting the individual IC circuit components. With an IC regulator, this gradient can be especially severe since power dissipation is large. Thermal regulation is the effect of these temperature gradients on output voltage (in percentage output change) per Watt of power change in a specified time. Thermal regulation error is independent of electrical regulation or temperature coefficient, and occurs within 5 ms to 50 ms after a change in power dissipation. Thermal regulation depends on IC layout as well as electrical design. The thermal regulation of a voltage regulator is defined as the percentage change of V_{OUT}, per Watt, within the first 10 ms after a step of power is applied. The LM137HV's specification is 0.02%/W, max.

In Figure 4, a typical LM137HV's output drifts only 3 mV (or 0.03% of V_{OUT} = −10V) when a 10W pulse is applied for 10 ms. This performance is thus well inside the specification limit of 0.02%/W x 10W = 0.2% max. When the 10W pulse is ended, the thermal regulation again shows a 3 mV step as the LM137HV chip cools off. Note that the load regulation error of about 8 mV (0.08%) is additional to the thermal regulation error. In Figure 5, when the 10W pulse is applied for 100 ms, the output drifts only slightly beyond the drift in the first 10 ms, and the thermal error stays well within 0.1% (10 mV).

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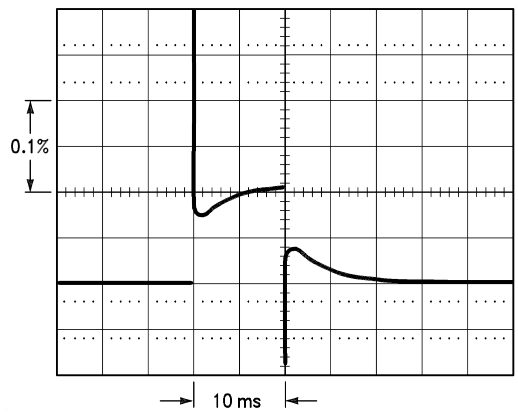
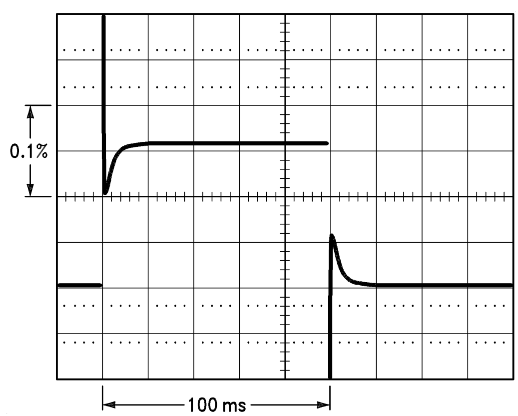


LM137HV, V_{OUT} = −10V
V_{IN}−V_{OUT} = −40V
I_L = 0A→0.25A→0A
Vertical sensitivity, 5 mV/div

Figure 4.



LM137HV, V_{OUT} = −10V
V_{IN}−V_{OUT} = −40V
I_L = 0A→0.25A→0A
Horizontal sensitivity, 20 ms/div

Figure 5.

When power is dissipated in an IC, a temperature gradient occurs across the IC chip affecting the individual IC circuit components. With an IC regulator, this gradient can be especially severe since power dissipation is large. Thermal regulation is the effect of these temperature gradients on output voltage (in percentage output change) per Watt of power change in a specified time. Thermal regulation error is independent of electrical regulation or temperature coefficient, and occurs within 5 ms to 50 ms after a change in power dissipation. Thermal regulation depends on IC layout as well as electrical design. The thermal regulation of a voltage regulator is defined as the percentage change of V_{OUT}, per Watt, within the first 10 ms after a step of power is applied. The LM137HV's specification is 0.02%/W, max.

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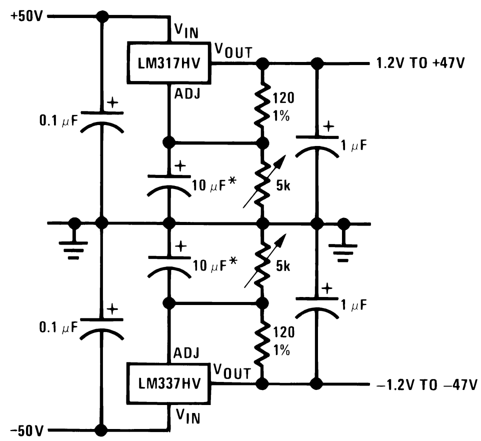
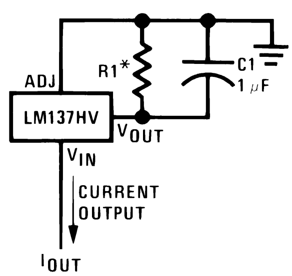
Typical Applications



Full output current not available at high input-output voltages
*The 10 μF capacitors are optional to improve ripple rejection

Figure 6. Adjustable High Voltage Regulator



$$I_{OUT} = \frac{V_{REF}}{R1}$$

* 0.8Ω ≤ R1 ≤ 120Ω

Figure 7. Current Regulator

When power is dissipated in an IC, a temperature gradient occurs across the IC chip affecting the individual IC circuit components. With an IC regulator, this gradient can be especially severe since power dissipation is large. Thermal regulation is the effect of these temperature gradients on output voltage (in percentage output change) per Watt of power change in a specified time. Thermal regulation error is independent of electrical regulation or temperature coefficient, and occurs within 5 ms to 50 ms after a change in power dissipation. Thermal regulation depends on IC layout as well as electrical design. The thermal regulation of a voltage regulator is defined as the percentage change of V_{OUT}, per Watt, within the first 10 ms after a step of power is applied. The LM137HV's specification is 0.02%/W, max.

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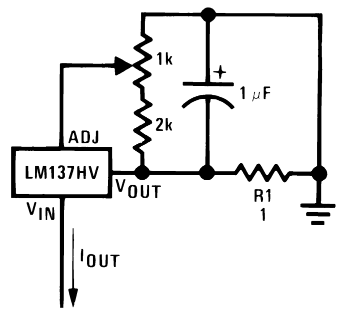
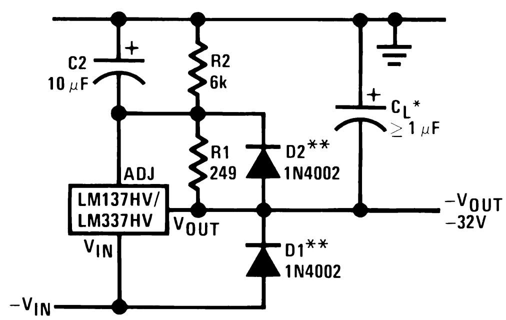


$$I_{OUT} = \left(\frac{1.5V}{R1}\right) \pm 15\% \text{ adjustable}$$

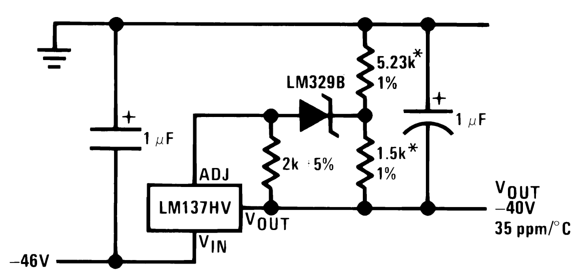
Figure 8. Adjustable Current Regulator



*When C_L is larger than 20 μF, D1 protects the LM137HV in case the input supply is shorted

**When C2 is larger than 10 μF and $-V_{OUT}$ is larger than −25V, D2 protects the LM137HV is case the output is shorted

Figure 9. Negative Regulator with Protection Diodes



*Use resistors with good tracking TC < 25 ppm/°C

Figure 10. High Stability −40V Regulator

Typical Performance Characteristics

(H and K-STEEL Package)

Load Regulation

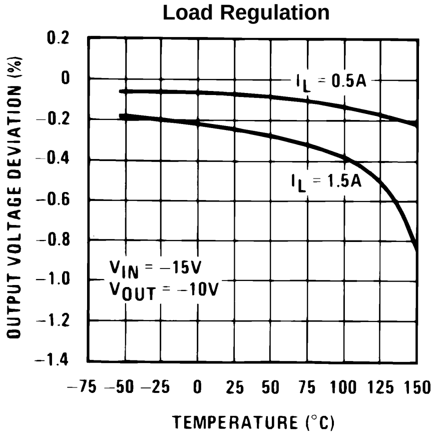


Figure 11.

Current Limit

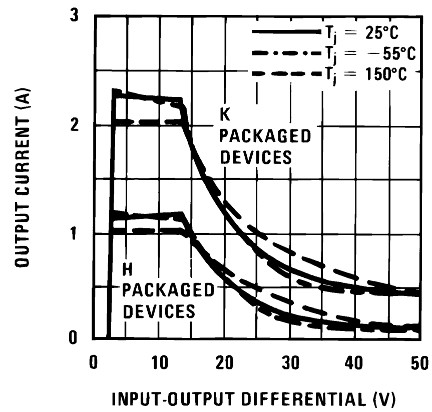


Figure 12.

Adjustment Current

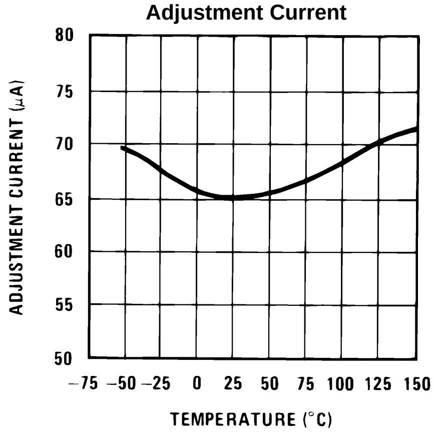


Figure 13.

Dropout Voltage

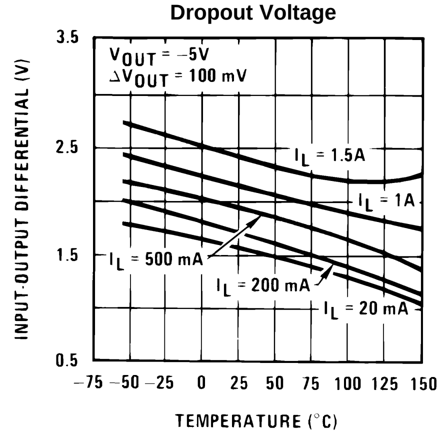


Figure 14.

Temperature Stability

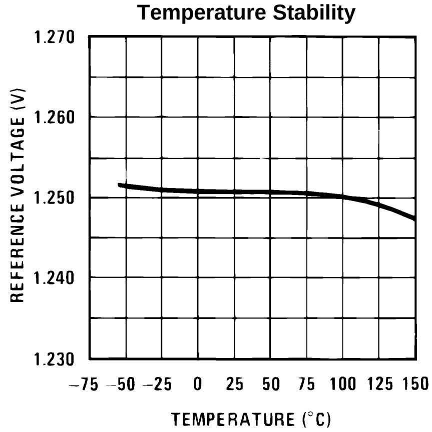


Figure 15.

Minimum Operating Current

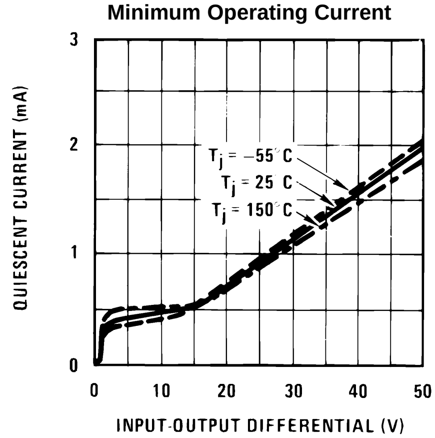


Figure 16.

Typical Performance Characteristics (continued)

(H and K-STEEL Package)

Ripple Rejection

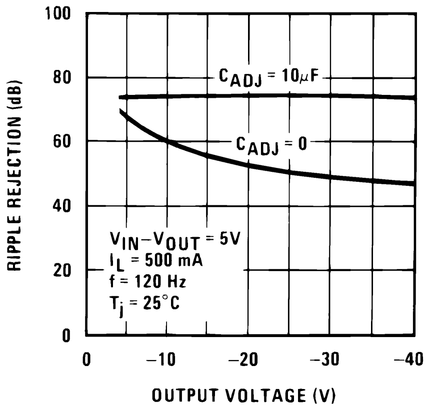


Figure 17.

Ripple Rejection

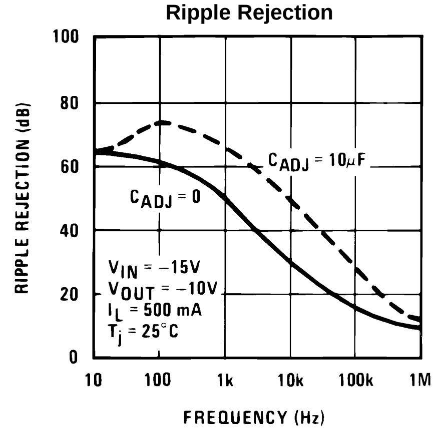


Figure 18.

Ripple Rejection

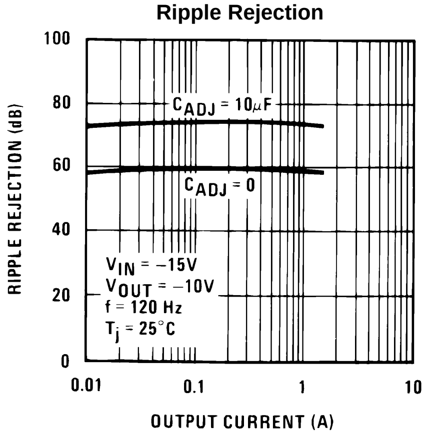


Figure 19.

Output Impedance

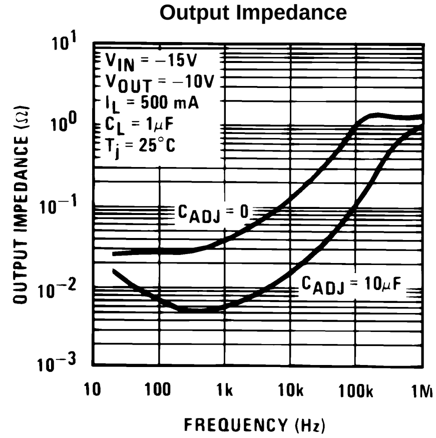


Figure 20.

Line Transient Response

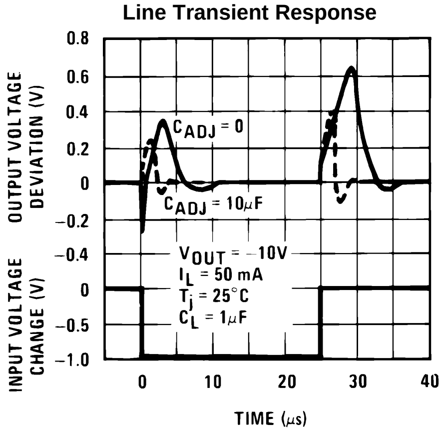


Figure 21.

Load Transient Response

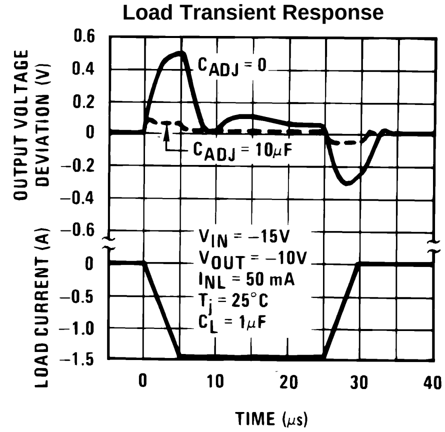


Figure 22.

REVISION HISTORY

Date Released	Revision	Section	Changes
12/16/2010	A	New Release, Corporate format	2 MDS data sheets converted into one Corp. Data sheet format. MNLM137HV-K rev 0A0, MNLM137HV-H rev 2A0 MDS datasheets will be archived.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM137HVH/883	ACTIVE	TO	NDT	3	20	TBD	POST-PLATE	Level-1-NA-UNLIM	-55 to 150	LM137HVH/883 Q ACO LM137HVH/883 Q >T	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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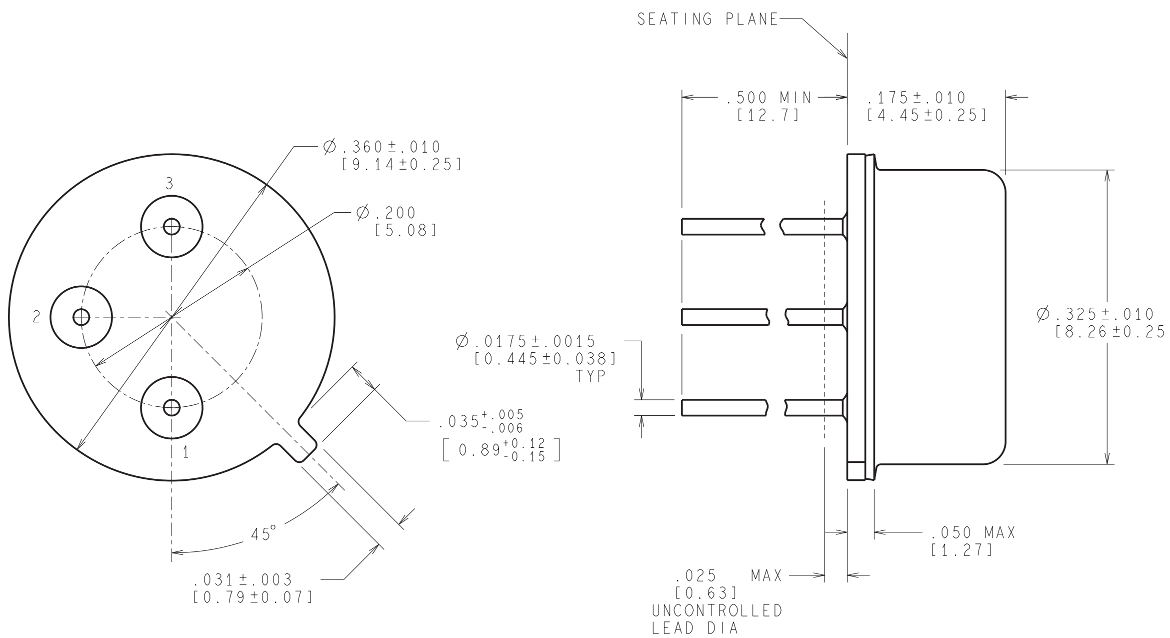
OTHER QUALIFIED VERSIONS OF LM137HVQML, LM137HVQML-SP :

- Military: LM137HVQML
- Space: LM137HVQML-SP

NOTE: Qualified Version Definitions:

- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

NDT0003A



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